

YO999247DIV

30. (Amended) An integrated circuit structure comprising:

a substrate;

an opening in said substrate, said opening consisting of a first rectangular portion and a second rectangular portion, wherein said second rectangular portion has larger dimensions than said first rectangular portion; and

a conductor filling said opening.

35. (Amended) An integrated circuit structure comprising:

a substrate;

an opening in said substrate, said opening consisting of a first rectangular portion, a second rectangular portion, and a third rectangular portion, wherein said second rectangular portion has larger dimensions than said first rectangular portion and said third rectangular portion; and

a conductor filling said opening.

Please add the following new claims:

39. The integrated circuit in claim 35, wherein said first rectangular portion and said third rectangular portion have different dimensions.

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40. An integrated circuit structure comprising:

a substrate;

a bottle-shaped opening in said substrate, said bottle-shaped opening comprising a first rectangular portion and a second rectangular portion, wherein said second rectangular portion has larger dimensions than said first rectangular portion; and

a conductor filling said opening.

41. The integrated circuit in claim 40, wherein said second rectangular portion is deeper in said opening than said first rectangular portion.

42. The integrated circuit in claim 40, wherein said first rectangular portion is deeper in said opening than said second rectangular portion.

43. The integrated circuit in claim 40, wherein said lateral openings increase a surface area of said trench capacitor.

44. The integrated circuit in claim 40, wherein said lateral openings increase a capacitance of said structure.